

ULP, *Ultra Low-Profile*, Aluminum Electrolytic Capacitors New Product Intro



ENERGIZING IDEAS

**CORNELL
DUBILIER**

Traditional methods of low-profile bulk storage consume valuable PCB space!

- A single ULP has the same bulk storage capacitance as dozens of solid tantalum chip caps, depending on values!
- About 70% less board space than ULP alternatives!
- Eliminates wasted space between components in bulk arrays

**HIGHER BULK STORAGE.
WITHOUT THE BULK.**

Ultra-low profile
2mm and 3mm thin

Near hermetic and
No dry-out

Replaces banks of
solid tantalum capacitors

3,000 Hc. life at 85 °C
without voltage derating

**INTRODUCING THE LATEST IN
ULTRA-LOW PROFILE CAPACITANCE.**

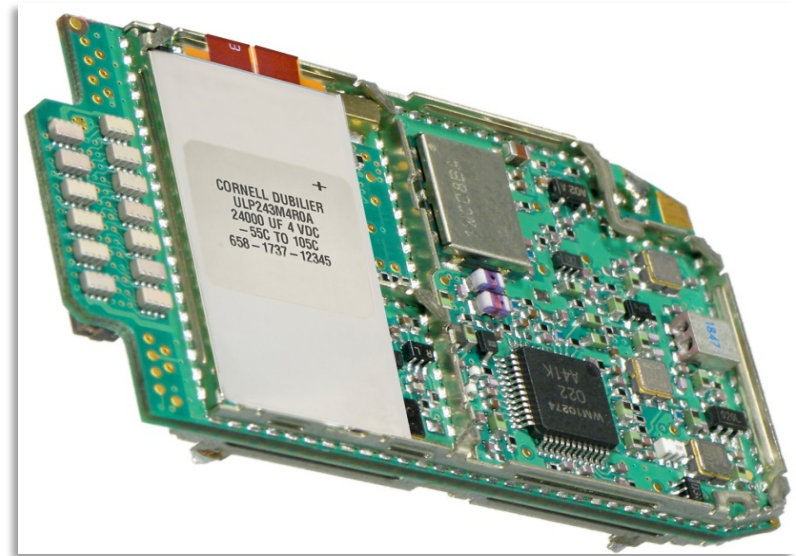
What do you get when you take the energy density of an aluminum electrolytic and engineer it to fit a rectangular case that is 2mm or 3mm thin? The ULP. A capacitor that takes up to 70% less board space when compared to solid tantalum capacitors. For hold-up applications the size and cost savings are extraordinary.

CDE CORNELL DUBILIER
ENGINEERING

For technical information and samples visit cde.com/ULP

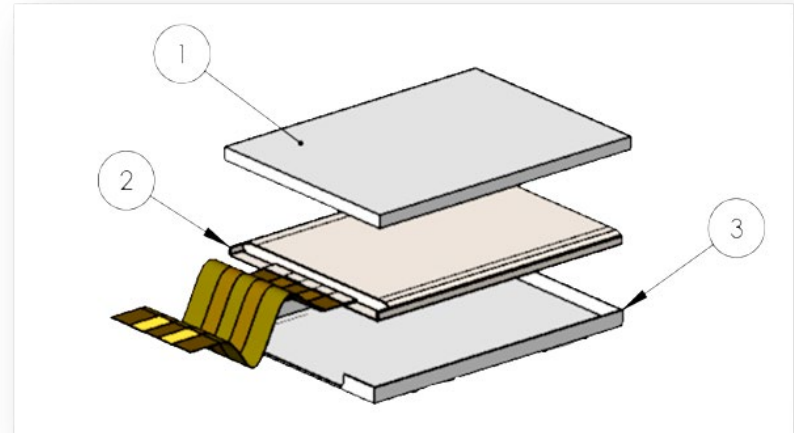
Smaller, more reliable circuits are possible with ULP, Ultra Low-Profile Capacitors.

- Lower in height than V-Chip SMT aluminum electrolytics and comparable height profile to solid tantalums with much greater bulk storage capability per unit area
- Provides high bulk storage capacitance in the least amount of space
- Overall size and weight of finished board is reduced
- Reduces component count, increases reliability



Keys to high performance and space savings

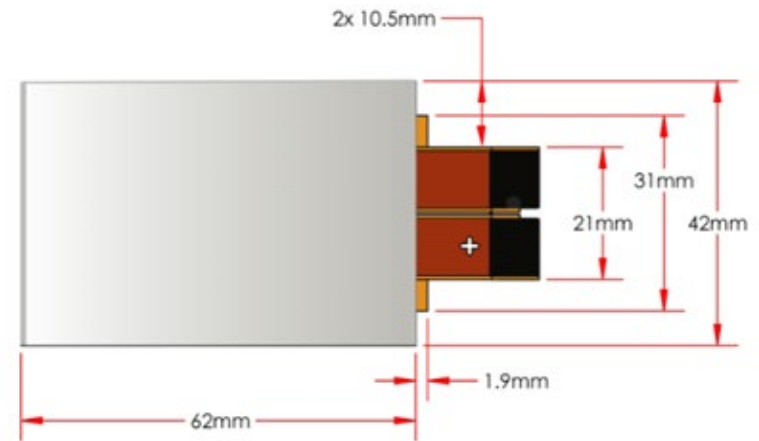
- Superior performance of an aluminum electrolytic in a low-profile package
 - 3,000 hr. life @ 85 °C
 - -40 to 85 °C at full-rated voltage
- Higher capacitance density due to unique packaging and seal system
 - Up to 0.4J/cc energy density
- Primary seal is a near-hermetic heat-sealed polymer. No rubber gaskets or grommets!



1. Case cover
2. Heat-sealed capacitor pouch
3. Bottom cover

Mechanical design characteristics.

- Available in two case thicknesses of 2.2 or 3.2 mm with a footprint of 62 x 42mm
- Flex (FPC) Lead System allows on or off-board mounting
- Mating ZIF Connector
- Nickel-Silver outer case
 - Robust construction, 10g vibration rating
- Light weight
 - 2.2mm (17g)
 - 3.3mm (22g)



Mating Molex Connector
05227 12079



ULP Ultra Low-Profile series includes 16 values/voltage combinations.

Capacitance from 500 μ F to 24,000 μ F, 4 to 63 WVDC

WV (v)	ULP (2mm)	ULP (3mm)
	85 °C Cap (μ F)	85 °C Cap (μ F)
4.0	7,800	24,000
6.3	6,600	20,000
10	5,200	15,000
16	3,600	11,000
25	2,300	6,900
35	1,400	4,400
50	700	2,200
63	500	1,500

Designed for *maximum* capacitance in the *smallest* package.

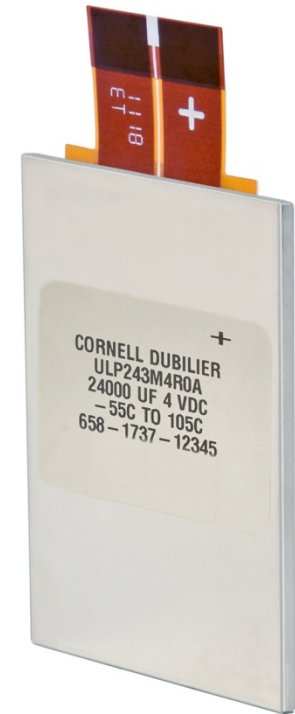
ULP capacitors allows designers to “think thin,” while achieving higher end-product performance...

- Bulk storage in portable devices
- Compact power supplies
 - Consumer
 - Industrial
 - Mil/Aero



ULP Ultra Low-Profile Series Summary

- Ultra-thin package design: 2 or 3mm
- One ULP capacitor has the same bulk storage capacity as dozens of solid tantalum chips, depending on values.
 - Not an alternative to hybrid tantalums or high ripple current types
- Up to 0.4J/cc energy density, saves space
- Values from 500 μ F to 24,000 μ F;
4 to 63 WVDC
- Rated at 3,000 hours at 85 °C
- Reduce size, weight & cost
- Increases reliability – one device vs. many; fewer PCB connection points



Thank You!